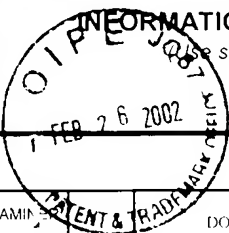


<b>INFORMATION DISCLOSURE CITATION</b> (Use several sheets if necessary)	ATTY DOCKET NO. 11675.184.1	SERIAL NO. 10/033.233
	Salman Akram	
	FILING December 28, 2001	GROUP Unknown



**U.S. PATENT DOCUMENTS**

*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
KN	1.	6.011.304	1/2000	Mertol	257	706	
KN	2.	6.215.180	4/2001	Chen, et al.	257	720	
KN	3.	5.583.378	12/1996	Marrs, et al.	257	710	
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KN	11.	5.475.040	12/1995	Jamison, et al.	536	513	

**FOREIGN PATENT DOCUMENTS**

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
KN	12.	JP362023138A	1/1987	Japan			✓	

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KN	13.	R. Hundadi, et al., "High Thermal Conductivity Greases.: pp. 28-32, Advanced Packaging, April 1999.
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EXAMINER <i>K. H. H. H. H. H.</i>	DATE CONSIDERED 12/16/02
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